# Notes in handling DSPACK

1. DSPACK was developed for the emulation test or system development purpose only. Therefore, Electrical Appliance and Material Safety Law or EMI standards do not approve the adapter.

2. When DSPACK is taken out of a packing box, press the product lightly by a finger, and then remove the packing materials first. Check if pins are damaged.

3. While a packing box has been kept under ambient temperature higher than 50  for long time, the box might be deformed. The storage place should be free from sunlight, and room temperature should be 40  or lower.

4. Cleaning for DSPACK should not be done. The cleaning materials and flux will contaminate in DSPACK due to the construction of the adapter. Cleaning for DIP components should not be done with DSPACK since flux for soldering DIP components will penetrate into DSPACK through guide pinholes.

5. A torque driver should be used for fixing DSPACK on to PWB. 4 screws should be loosely fastened first, then tightly fasten the screws with equal torque. Fastening torque should be 0.054 Nm. (0.55kg f cm) Max. Excess tightening torque for one screw only will cause poor contact.

6. The screwdriver attached or a torque driver should be used for fixing the top cover on to the spacer of DSPACK. 4 screws should be loosely fastened first, then tightly fasten the screws with equal torque. Fastening torque   should be 0.054 N m (0.055kgf cm) Max. Excess tightening torque for one screw only will cause poor contact.

7. Refer to the technical drawing of DSPACK for fixing it on to PWB. The underneath of nuts is runner restriction areas.

8. Foreign materials and dusts on solder balls and, also oxidized solder balls will cause poor contact with pogo pin. Remove those before loading BGA package into the adapter.

9. Fixing screws and nuts for the top cover and PWB should be loosened while an emulation device is kept in a shelf for long time.

10. DSPACK should be used for emulation test purpose only.

11. DSPACK cannot withstand under vibration or shock environment.


DSPACK were developed for test or emulation applications.


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